



United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

DATE MAILED: 07/17/2003

09/612,176 07/08/2000 Thomas L. Ritzdorf 291958117US 7779 25096 7590 07/17/2003 PERKINS COIE LLP PATENT-SEA P.O. BOX 1247 SEATTLE, WA 98111-1247 ART UNIT PAPER NUMBER	PPLICATION NO.	N NO. FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
PERKINS COIE LLP PATENT-SEA P.O. BOX 1247 SEATTLE, WA 98111-1247 EXAMINER SMITH, ZANDRA V	09/612,176	(7/08/2000	Thomas L. Ritzdorf	291958117US 7779	
PATENT-SEA P.O. BOX 1247 SEATTLE, WA 98111-1247	25096	7590	07/17/2003			
P.O. BOX 1247 SEATTLE, WA 98111-1247	PERKINS	COIE LL	P	EXAMINER		
SEATTLE, WA 98111-1247	PATENT-S	EA		SMITH, ZANDRA V		
	P.O. BOX	1247				
	SEATTLE, WA 98111-1247					
					2877	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application N	Applicant(a)					
	Application No.	Applicant(s)					
Office Action Comments	.09/612,176	RITZDORF ET AL.					
Office Action Summary	Examiner	Art Unit					
	Zandra V. Smith	2877					
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the	correspondence address					
A SHORTENED STATUTORY PERIOD FOR REPL' THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.1: after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period of the period of the period for reply within the set or extended period for reply will, by statute - Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b). Status	36(a). In no event, however, may a reply be y within the statutory minimum of thirty (30) d vill apply and will expire SIX (6) MONTHS fro, cause the application to become ABANDO	timely filed ays will be considered timely. m the mailing date of this communication. IED (35 U.S.C.§ 133).					
1) Responsive to communication(s) filed on 21 A	<u> April 2003</u> .						
2a)⊠ This action is FINAL . 2b)□ Th	is action is non-final.						
3) Since this application is in condition for allows closed in accordance with the practice under Disposition of Claims							
4) Claim(s) 2.3,5,6,12-16,20,23-26 and 31-47 is/	are pending in the application.						
4a) Of the above claim(s) is/are withdraw							
5) Claim(s) 2.3.5,6,12,20,23-26 and 47 is/are allo							
6) Claim(s) 13,15,16,31,33,34,37-40,42,43 and 4							
7) Claim(s) <u>14,32,35,36,41,44 and 45</u> is/are objection							
8) Claim(s) are subject to restriction and/o							
Application Papers							
9)☐ The specification is objected to by the Examine							
10) ☐ The drawing(s) filed on is/are: a) ☐ acce							
Applicant may not request that any objection to th							
11) The proposed drawing correction filed on		proved by the Examiner.					
If approved, corrected drawings are required in re							
12) The oath or declaration is objected to by the Ex	caminer.						
Priority under 35 U.S.C. §§ 119 and 120		(A) (A) (B)					
13) Acknowledgment is made of a claim for foreign	n priority under 35 U.S.C. § 119	9(a)-(d) or (i).					
a) ☐ All b) ☐ Some * c) ☐ None of:	la barra barra manabinad						
1. Certified copies of the priority document		ation No					
2. Certified copies of the priority document							
3. Copies of the certified copies of the priorapplication from the International But* See the attached detailed Office action for a list	ıreau (PCT Rule 17.2(a)).						
14) ☐ Acknowledgment is made of a claim for domest	ic priority under 35 U.S.C. § 11	9(e) (to a provisional application).					
 a) ☐ The translation of the foreign language prediction 15)☐ Acknowledgment is made of a claim for domest 							
Attachment(s)							
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449) Paper No(s) _ 	5) Notice of Inform	ary (PTO-413) Paper No(s) al Patent Application (PTO-152)					
S Patent and Trademark Office							

Application/Control Number: 09/612,176

Art Unit: 2877

DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) do not apply to the examination of this application as the application being examined was not (1) filed on or after November 29, 2000, or (2) voluntarily published under 35 U.S.C. 122(b). Therefore, this application is examined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

Claims 13 and 15-16 are rejected under 35 U.S.C. 102(e) as being anticipated by Akimoto et al. (6,004,047).

As to claim 13, Akimoto discloses a photoresist processing system, comprising:

an in-line metrology unit having a space for receiving a work-piece for measuring a condition of a first layer of the work-piece and generating a condition signal;

a control connected to the metrology unit;

multiple process units providing space to receive the work-piece and perform material application processes, wherein a condition signal from the metrology unit influences process conditions (col. 6, lines 1-20 and col. 7, line 58-col. 8, line 10); and

Art Unit: 2877

a transport unit to receive the work piece from one of the process units and the metrology unit and move the work piece to another process unit (col. 6, lines 30-42 and col. 8, lines 15-20).

As to claims 15-16, Akimoto discloses everything claimed, as applied above, in addition the work pieces are processed in one processing tool and then other processing tools.

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 31, 33-34, 37-40, 42-43, and 46 are rejected under 35 U.S.C. 102(b) as being anticipated by *Moslehi* (5,719,495).

As to claim 31, Moslehi discloses an apparatus for semiconductor device fabrication diagnosis and prognosis, comprising:

a metrology unit (112) to measure a condition of at least one conductive layer (col. 5, line 59) and generate a condition signal (col. 6, lines 55-60, col. 8, line 5, and col. 9, lines 15-25);

an electrochemical processing unit to apply a conductive material to the conductive layer (col. 5, lines 55-65); and

a control unit coupled between the metrology unit and the processing unit to receive the condition signal from the metrology unit and transmit a control signal, the control signal influencing the manner in which the conduction material is applied to the conductive layer (col. 4, lines 24-29, col. 7, lines 51-60, and col. 8, lines 10-15).

As to claims 33 and 42, Moslehi discloses everything claimed, as applied above, in addition a material deposition unit is provided (col. 8, lines 55-65 and col. 9, lines 15-25).

As to claims 34 and 43, Moslehi discloses everything claimed, as applied above, in addition the metrology unit detects a condition of the conductive layer (col. 8, lines 55-65 and fig. 4).

Application/Control Number: 09/612,176

Art Unit: 2877

As to claims 37-38 and 46 Moslehi discloses everything claimed, as applied above, in addition the metrology unit and the processing unit are housed separately and are virtually coupled (see fig. 4).

As to claim 39, Moslehi discloses everything claimed, as applied above, in addition the control signal influences a uniformity with which the conductive material is applied (col. 4, lines 24-29, col. 7, lines 51-60, and col. 8, lines 10-15).

As to claim 40, Moslehi discloses an apparatus for semiconductor device fabrication diagnosis and prognosis, comprising:

a metrology unit (112) to measure a condition of at least one conductive layer (col. 5, line 59) and generate a condition signal (col. 6, lines 55-60, col. 8, line 5, and col. 9, lines 15-25);

a processing unit to apply a conductive material to the conductive layer, the process including an enhancement process (col. 4, lines 23-30 and col. 5, lines 55-65); and

a control unit coupled between the metrology unit and the processing unit to receive the condition signal from the metrology unit and transmit a control signal, the control signal influencing the manner in which the conduction material is applied to the conductive layer (col. 4, lines 24-29, col. 7, lines 51-60, and col. 8, lines 10-15).

Allowable Subject Matter

Claims 2-3, 5-6, 12, 20, 23-26, and 47 are allowable over the prior art of record.

Claims 14, 32, 35-36, 41, and 44-45 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Page 5

The following is a statement of reasons for the indication of allowable subject matter: the prior art of record, taken alone or in combination, fails to disclose or render a seed layer enhancement unit, an electroplating reactor, movement of the wafer to a non-compliance unit in response to a signal from a metrology unit, use of a condition signal to adjust the current between the anode and cathode or determining seed layer thickness.

Response to Arguments

Applicant's arguments filed 21 April 2003 have been fully considered but they are not persuasive. Applicant's representative argues that Akimoto does not meet the limitation of claim 13 because Akimoto measures the thickness of the film on the surface of the wafer without taking the work-piece out of the processing system. Claim 13 requires at least two processing tools and movement of the wafer from one of the processing tool to a metrology unit to determine a condition of a layer on the work piece then modifying a process parameter in response to the signal from the metrology unit. Akimoto provides various processing unit (tools) (col. 5, line 68) in a process system to perform various processes on a work piece. The wafer is moved from one process unit to a metrology unit and in response to a signal from the metrology unit, a process parameter is modified (col. 6, lines 1-20 and col. 7, line 58-col. 8, line 10).

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Zandra V. Smith whose telephone number is (703) 305-7776. The examiner can normally be reached on 8:00 a.m. - 4:30 p.m..

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Frank G. Font can be reached on (703)308-4881. The fax phone numbers for the Application/Control Number: 09/612,176

Art Unit: 2877

organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 305-05\(\beta 0. \end{array}

Primary Examiner
Art Unit 2877

July 11, 2003

Page 6